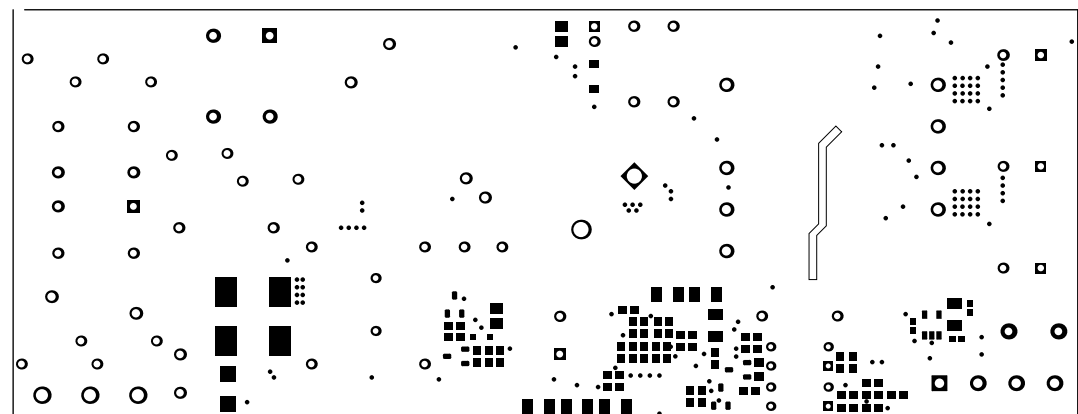
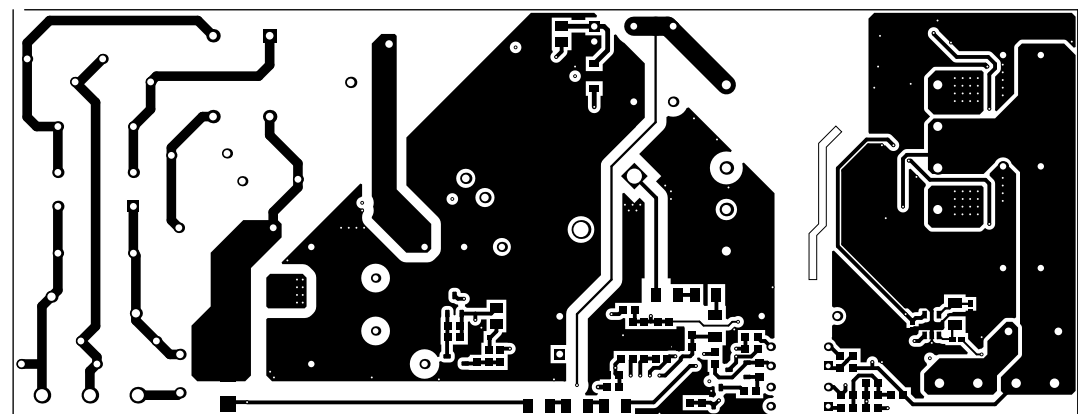


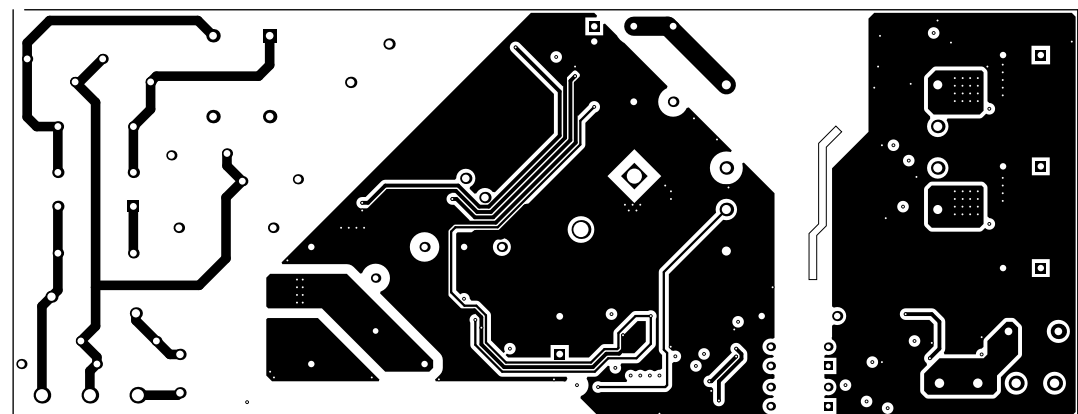
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21251	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 1/26/2018 3:45:16 PM	TEXAS INSTRUMENTS	



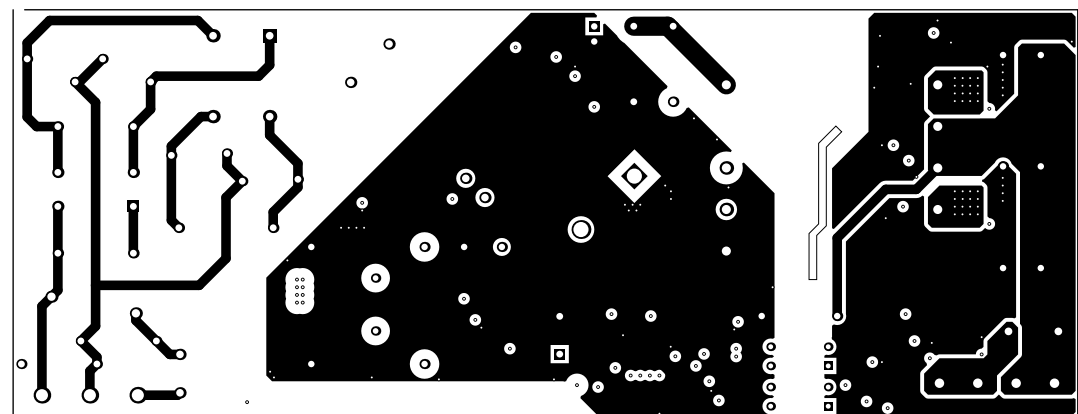
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21251	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 1/26/2018 3:45:17 PM	TEXAS INSTRUMENTS	



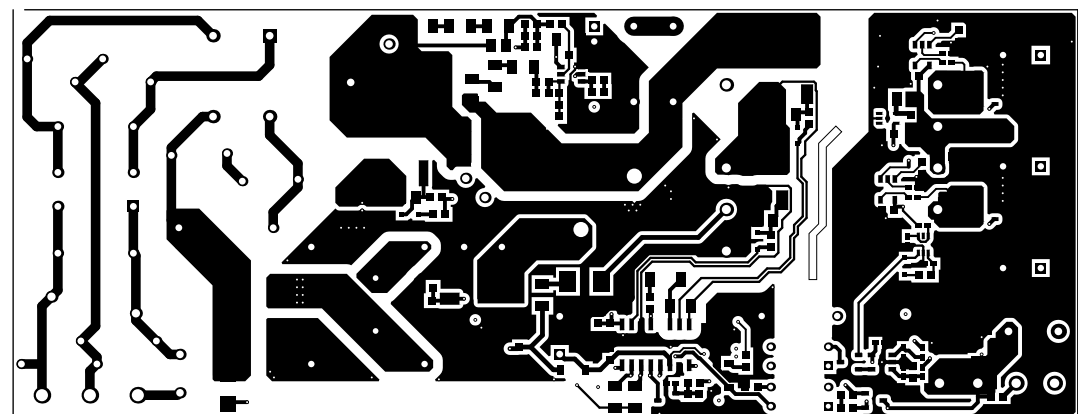
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21251	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 1/26/2018 3:45:19 PM	TEXAS INSTRUMENTS	



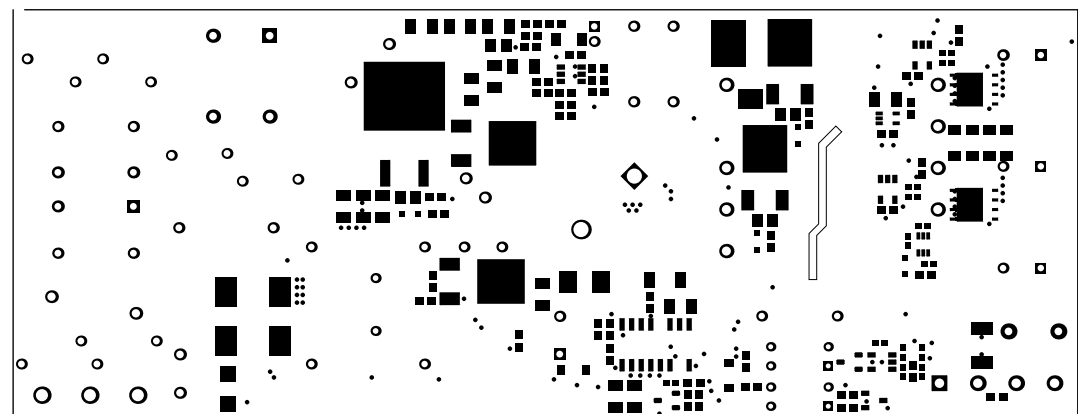
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21251	REV: B	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 1	GENERATED : 1/26/2018 3:45:20 PM		TEXAS INSTRUMENTS



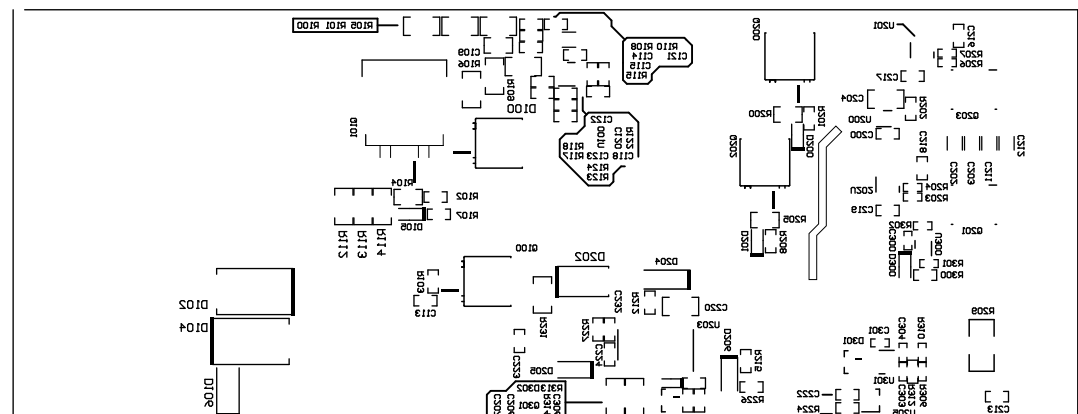
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21251	REV: B	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 2	GENERATED : 1/26/2018 3:45:21 PM		TEXAS INSTRUMENTS



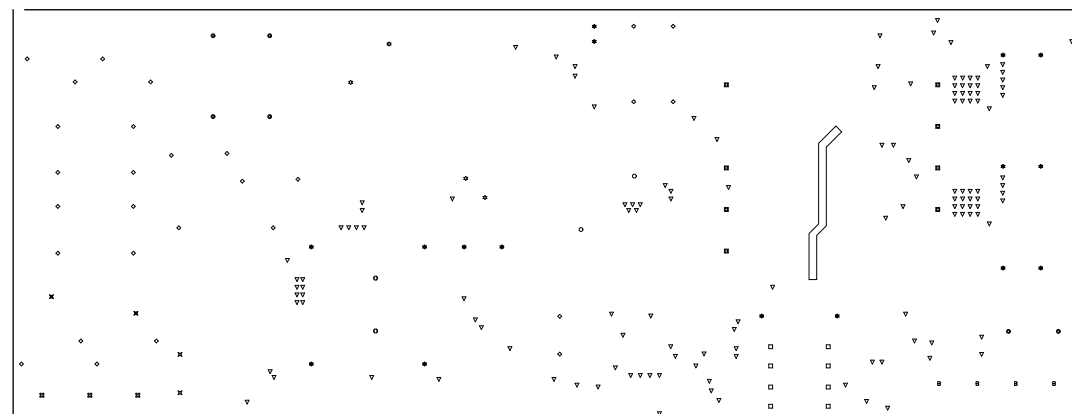
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21251	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 1/26/2018 3:45:23 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21251	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 1/26/2018 3:45:24 PM	TEXAS INSTRUMENTS	

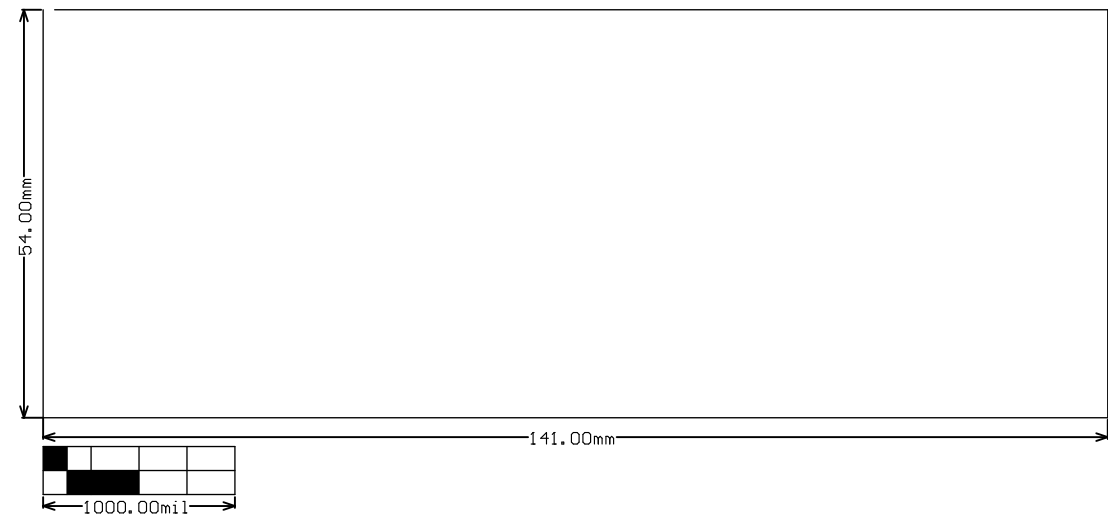


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21251	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 1/26/2018 3:45:26 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
▽	134	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
□	8	25.59mil (0.650mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	29.53mil (0.750mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	16	33.47mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
◇	28	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	4	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	+/-1.18mil
⊗	6	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	2	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	8	47.24mil (1.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	4	49.21mil (1.250mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	3	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
○	2	78.74mil (2.000mm)	PTH	Round	Top Layer - Bottom Layer	
	219 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21251	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 1/26/2018 3:45:27 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP21251	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 1/26/2018 3:45:29 PM	TEXAS INSTRUMENTS	

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